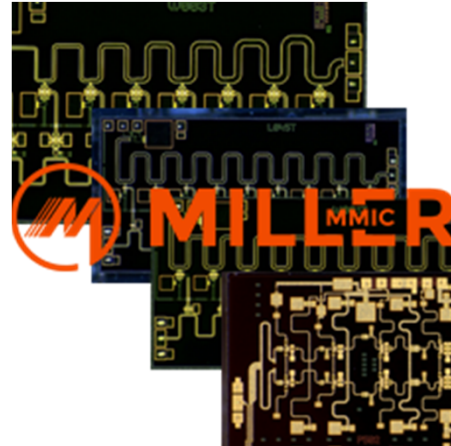


**Features**

- SP2T Absorptive design
- Frequency:DC-20GHz
- Isolation: 50dB
- Insertion Loss: 1.2dB
- Return Loss (ON):18dB
- Control Voltage:0/-5V
- Switching Speed:15ns
- Die Size: 1.5x1.5x 0.1 mm


**Typical Applications**

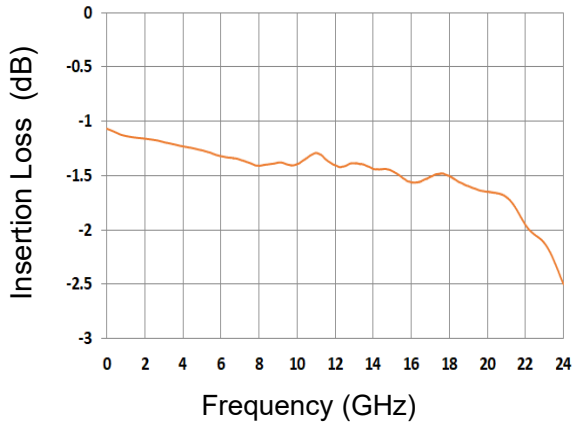
- Voltage control no current
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

**Electrical Specifications**
**TA = +25°C**

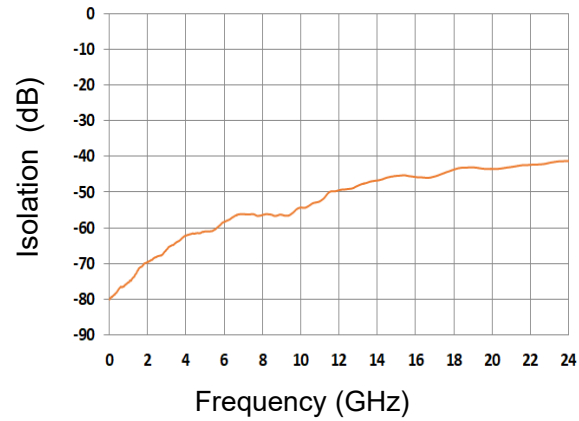
Parameters	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
<b>Frequency</b>	<b>DC-6</b>		<b>6-20</b>				<b>GHz</b>
<b>Insertion Loss</b>		<b>1.2</b>	<b>1.5</b>		<b>1.4</b>	<b>1.7</b>	<b>dB</b>
<b>Isolation</b>	<b>55</b>	<b>65</b>		<b>40</b>	<b>50</b>		<b>dB</b>
<b>Return Loss (ON State)</b>	<b>18</b>	<b>20</b>		<b>18</b>	<b>22</b>		<b>dB</b>
<b>Output Return Loss (OFF State)</b>	<b>18</b>	<b>19</b>		<b>18</b>	<b>20</b>		<b>dB</b>
<b>Input P-1</b>		<b>18</b>			<b>18</b>		<b>dBm</b>
<b>RF Input power</b>			<b>30</b>			<b>30</b>	<b>dBm</b>
<b>IIP3</b>		<b>28</b>			<b>28</b>		<b>dBm</b>
<b>Switching Speed</b>	<b>15</b>						<b>ns</b>



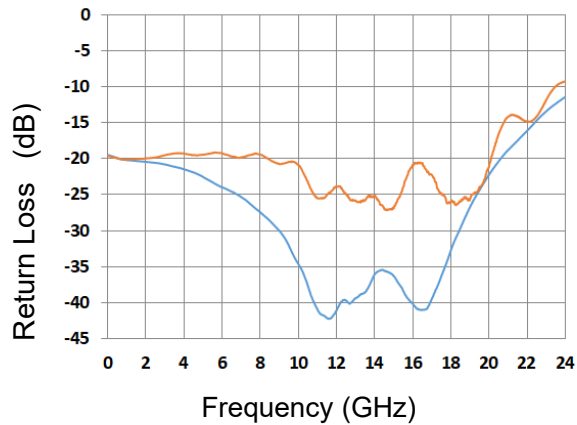
### Insertion Loss @25°C



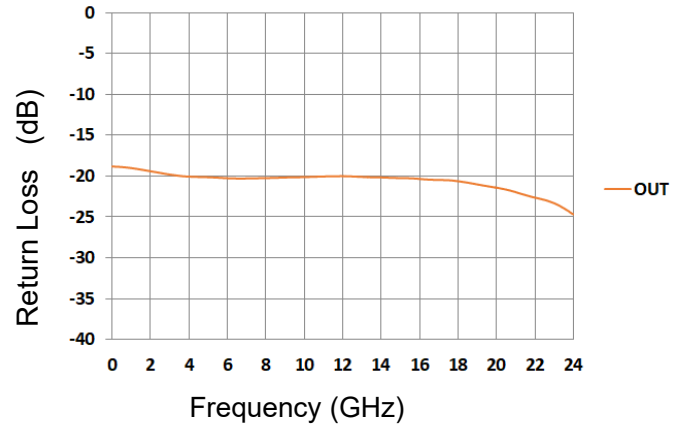
### Isolation @25°C



### Return Loss (ON) @25°C

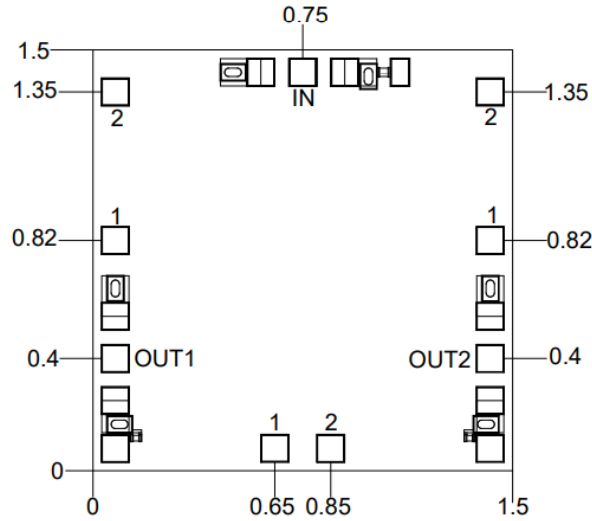


### Output Return Loss (OFF) @25°C





### Outline Drawing: All Dimensions in mm

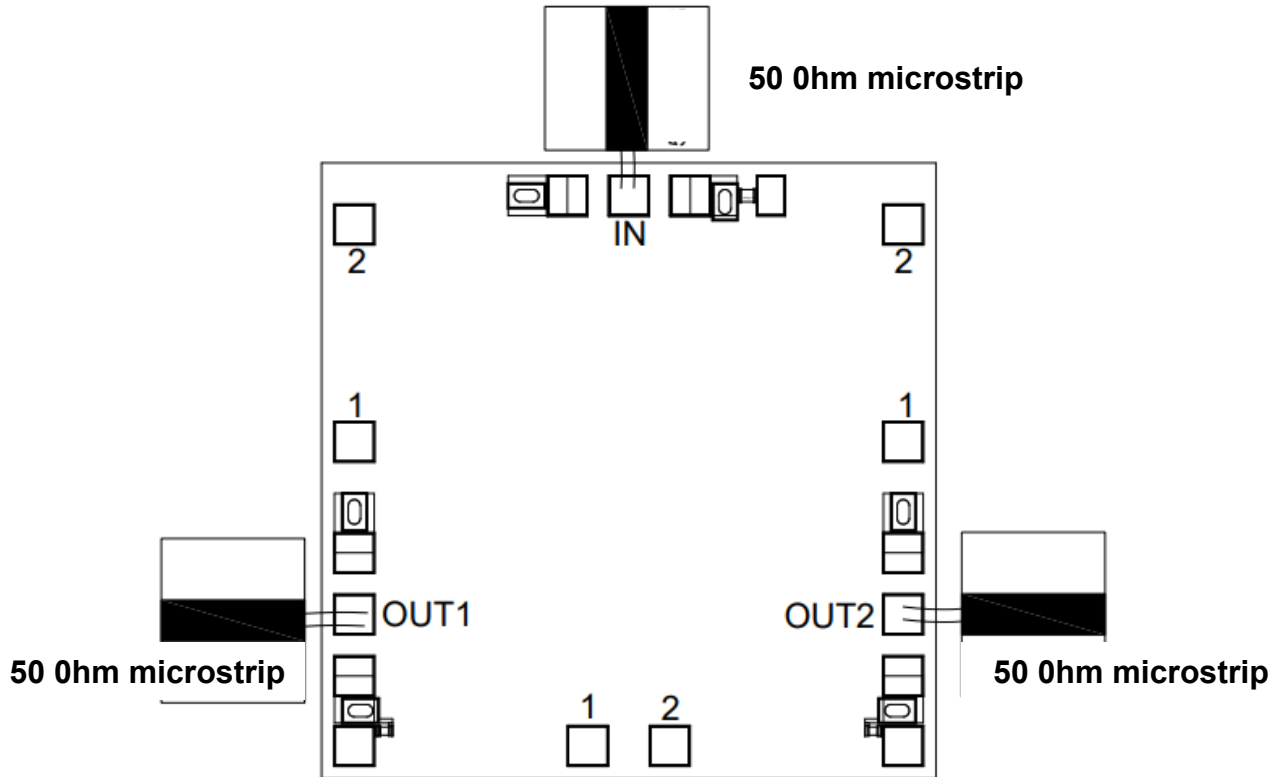


### True Table

Control Voltage		State	
1	2	IN-OUT1	IN-OUT2
0	-5	ON	OFF
-5	0	OFF	ON



### Assembly Drawing



#### Notes:

1. Die thickness: 100um
2. Typical bond pad is 100\*100  $\mu\text{m}^2$
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

#### Maximum Ratings:

- 1.RF input power: +30dBm
- 2.Control Voltage: -8~+1V
3. Storage temperature: -65°C to +150°C
4. Operating temperature: -55°C to 125°C